

2SK3565

Switching Regulator Applications

Unit: mm

• Low drain-source ON resistance: $R_{DS}(ON) = 2.0 \Omega$ (typ.)

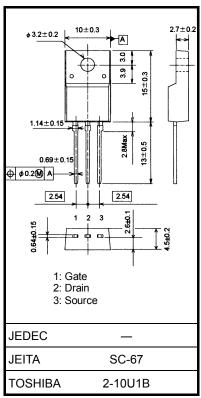
• High forward transfer admittance: |Y_{fs}| = 4.5 S (typ.)

• Low leakage current: $I_{DSS} = 100 \mu A (V_{DS} = 720 V)$

• Enhancement mode: V_{th} = 2.0 to 4.0 V (V_{DS} = 10 V, I_D = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	900	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	5		
	Pulse (t = 1 ms) (Note 1)	I _{DP}	15	Α	
Drain power dissipation (Tc = 25°C)		PD	45	W	
Single pulse avalanche energy (Note 2)		E _{AS}	595	mJ	
Avalanche current		I _{AR}	5	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	4.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

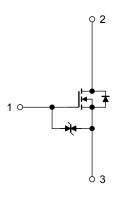
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}C(\text{Initial})$, L = 43.6 mH, $I_{AR} = 5.0 \text{ A}$, $R_G = 25 \Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



Electrical Characteristics (Ta = 25°C)

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source brea	akdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off curre	ent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μА
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	900	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 3 A	_	2.0	2.5	Ω
Forward transfer	admittance	Yfs	V _{DS} = 20 V, I _D = 3 A	2.0	4.5	_	S
Input capacitance	apacitance C _{iss}			_	1150	_	pF
Reverse transfer capacitance		C _{rss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	20	_	
Output capacitance		Coss		_	100	_	
Switching time	Rise time	t _r	$\begin{array}{c c} 10 \text{ V} \\ \text{VGS} \\ 0 \text{ V} \end{array}$ $\begin{array}{c c} \text{I}_D = 3 \text{ A} & \text{V}_{\text{OUT}} \\ \text{O} \\ \text{SO } \\ \text{M} \end{array}$ $\begin{array}{c c} \text{R}_L = \\ 66.7 \Omega \\ \text{V}_{DD} \approx 200 \text{ V} \end{array}$	_	30	_	
	Turn-on time	t _{on}		_	70	_	
	Fall time	t _f		_	60	_	ns
	Turn-off time	t _{off}	Duty \leq 1%, $t_W = 10 \mu s$	_	170	_	
Total gate charge		Qg		_	28	_	
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	17	_	nC
Gate-drain charge		Q _{gd}			11		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	15	Α
Forward voltage (diode)	V_{DSF}	$I_{DR} = 5 A$, $V_{GS} = 0 V$		_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V},$		900	_	ns
Reverse recovery charge	Qrr	dI _{DR} /dt = 100 A/μs	_	5.4	_	μС

Marking

